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TITLE: 360 I/O, FC-CLGA, 25 X 25 PKG, 1.27 PITCH 6 CAPS	DOCUMENT NO: 98ARE10580D	REV: B
	STANDARD: NON-JEDEC	
	SOT1610-2	17 DEC 2015



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. AREA OCCUPIED BY THE DIE AND UNDERFILL. ACTUAL SIZE OF THIS AREA MAY BE SMALLER THAN SHOWN.

4. MINIMUM CLEARANCE FROM THE PACKAGE EDGE TO THE CHIP CAPACITORS.

5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.
6. CAUTION MUST BE TAKEN NOT TO SHORT EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

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